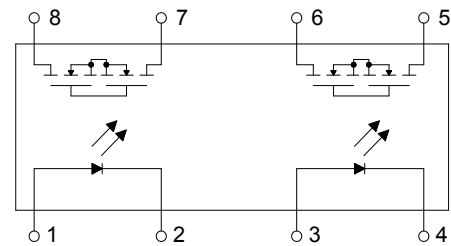


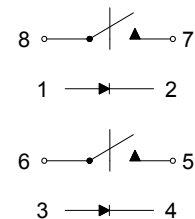
## ● Description

The NAQW216 series contains two normally open switches that can be used as two independent SPST relays or as one DPST relay. The relay is constructed using a GaAlAs LED for actuation control and an integrated monolithic dies for the switch output. The die, fabricated in a high-voltage dielectrically isolated technology, is comprised of a photodiode array, switch control circuitry and MOSFET switches.

## ● Schematic



DUAL 1 FORM A  
NORMALLY OPEN



## ● Features

1. Normally open, double pole single throw
2. Control 600V AC or DC voltage
3. Switch 120mA loads
4. Controls low-level analog signals
5. High sensitivity, low ON resistance
6. Low-level off state leakage current
7. High isolation voltage 5KV (DIP / SMD)
8. Pb free and RoHS compliant
9. MSL class 1
10. Agency Approvals :
  - UL Approved (No. E169586): UL1577
  - c-UL Approved (No. E169586)
  - VDE Approved (No. 40020973): DIN EN60747-5-5

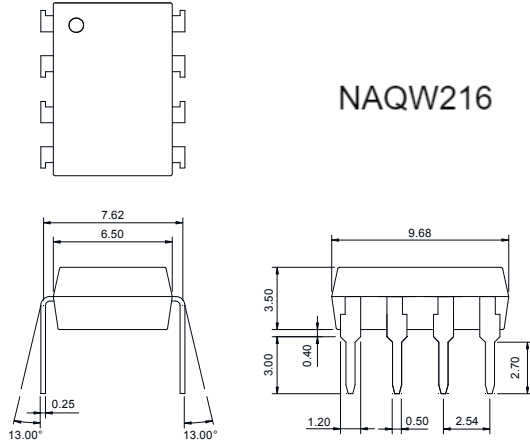
## ● Application

- Telecommunications (PC, electronic notepad)
- Modem
- Telephone equipment
- Security equipment
- Sensors
- Measuring and testing equipment
- Factory automation equipment
- High speed inspection machines

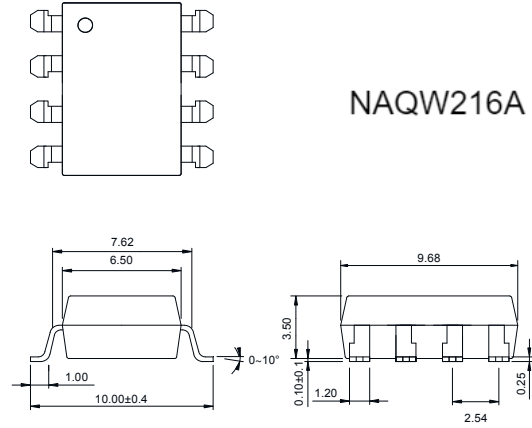
## ● Outside Dimension

Unit : mm

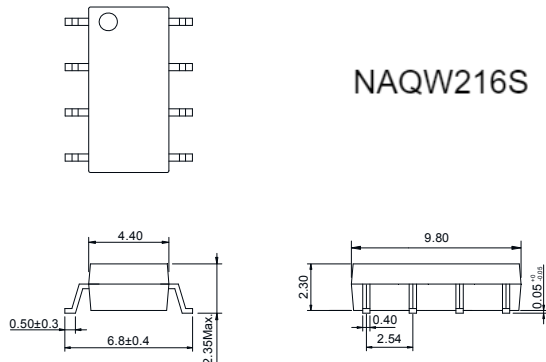
### 1. Dual-in-line type.



### 2. Surface mount type.

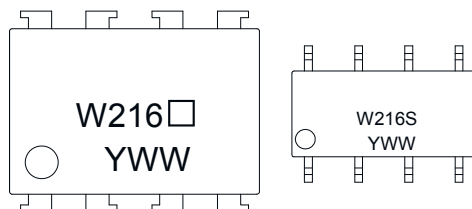


### 3. Small outline for surface mount type.



TOLERANCE : ±0.2mm

## ● Device Marking



## Notes :

W216□ □(Blank): DIP or SMD  
W216S S : SOP  
YWW Y : Year code / W : Week code

## ● Absolute Maximum Ratings

(Ta=25°C)

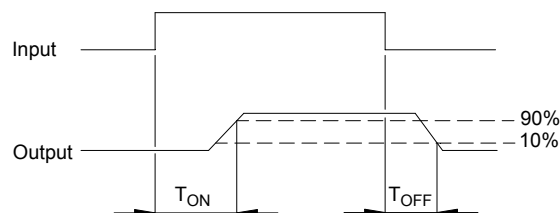
| Item                             |                            | Symbol    | Rating          | Unit           |
|----------------------------------|----------------------------|-----------|-----------------|----------------|
| Input                            | Continuous forward current | $I_F$     | 50              | mA             |
|                                  | Peak forward current       | $I_{FP}$  | 1               | A              |
|                                  | Reverse voltage            | $V_R$     | 5               | V              |
|                                  | Power dissipation          | $P_{in}$  | 100             | mW             |
|                                  | Derate linearly from 25°C  | -         | 1.3             | mW/°C          |
| Output                           | Breakdown voltage          | $V_B$     | 600             | V              |
|                                  | Continuous load current    | $I_L$     | 120             | mA             |
|                                  | Power dissipation          | $P_{out}$ | 500             | mW             |
| Isolation voltage                |                            | $V_{iso}$ | <b>NAQW216S</b> | <b>NAQW216</b> |
|                                  |                            |           | 1500Vrms        | 5000Vrms       |
| Isolation resistance (Vio=500V)  |                            | $R_{iso}$ | $\geq 10^{10}$  | $\Omega$       |
| Total power dissipation          |                            | $P_t$     | 550             | mW             |
| Derate linearly from 25°C        |                            | -         | 2.5             | mW/°C          |
| Operating temperature            |                            | $T_{opr}$ | -40 to +85      | °C             |
| Storage temperature              |                            | $T_{stg}$ | -40 to +125     | °C             |
| Junction temperature             |                            | $T_j$     | 100             | °C             |
| Soldering temperature 10 seconds |                            | $T_{sot}$ | 260             | °C             |

## ● Electro-optical Characteristics

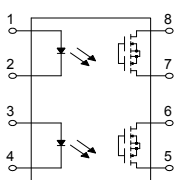
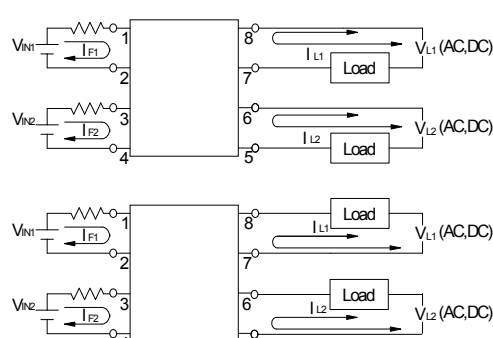
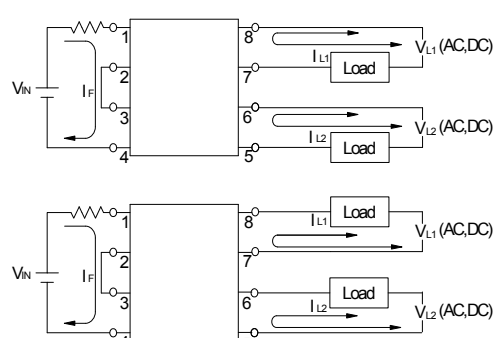
(Ta=25°C)

| Parameter       |                           | Symbol     | Conditions                              | Min. | Typ. | Max. | Unit          |
|-----------------|---------------------------|------------|-----------------------------------------|------|------|------|---------------|
| Input           | Forward voltage           | $V_F$      | $I_F=10\text{mA}$                       | -    | 1.2  | 1.5  | V             |
|                 | Operation input current   | $I_{FON}$  | $V_L=20\text{V}, I_L=100\text{mA}$      | -    | -    | 3.0  | mA            |
|                 | Recovery input current    | $I_{FOFF}$ | $V_L=20\text{V}, I_L \leq 5\mu\text{A}$ | 0.2  | -    | -    | mA            |
| Output          | Breakdown voltage         | $V_B$      | $I_B=50\mu\text{A}$                     | 600  | -    | -    | V             |
|                 | Off-state leakage current | $I_{LEAK}$ | $V_L=600\text{V}, I_F=0\text{mA}$       | -    | 0.2  | 1.0  | $\mu\text{A}$ |
| I/O capacitance |                           | $C_{iso}$  | $V_B=0\text{V}, f=1\text{MHz}$          | -    | 6    | -    | pF            |
| ON resistance   |                           | $R_{ON}$   | $I_F=10\text{mA}, I_L=100\text{mA}$     | -    | 35   | 80   | $\Omega$      |
| Turn-on time    |                           | $T_{ON}$   | $I_F=10\text{mA}, V_L=20\text{V}$       | -    | 0.3  | 1.0  | ms            |
| Turn-off time   |                           | $T_{OFF}$  | $I_L=100\text{mA}, t=10\text{ms}$       | -    | 0.1  | 1.5  | ms            |

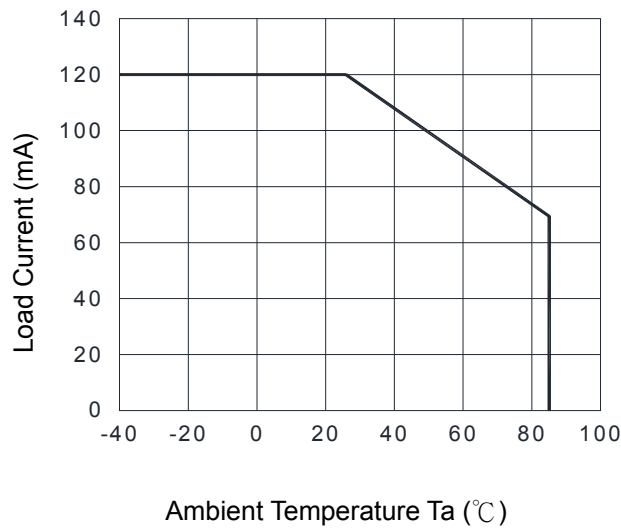
## ● Turn-on / Turn-off Time



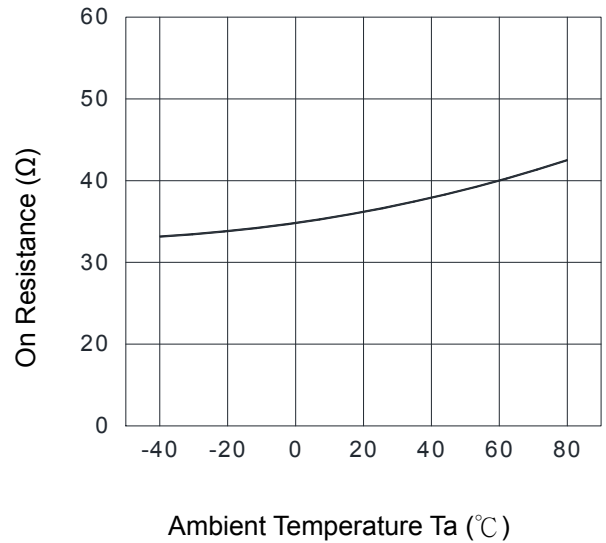
● Schematic and Wiring Diagrams

| Schematic                                                                         | Output Configuration | Load     | Connection | Wiring Diagrams                                                                                                                                                                                                                        |
|-----------------------------------------------------------------------------------|----------------------|----------|------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|  | 2a                   | AC<br>DC | -          | <p>(1) Two independent 1 Form A use</p>  <p>(2) 2 Form A use</p>  |

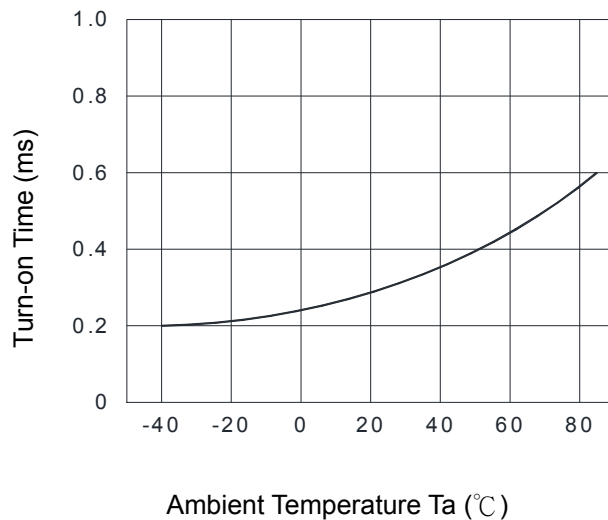
**Fig.1 Load Current vs. Ambient Temperature**



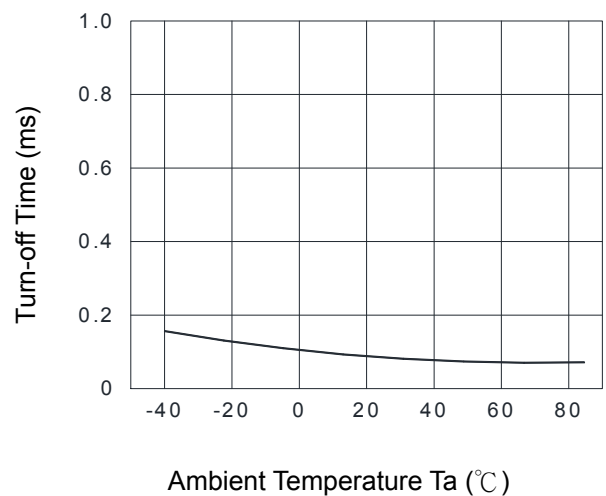
**Fig.2 On Resistance vs. Ambient Temperature**



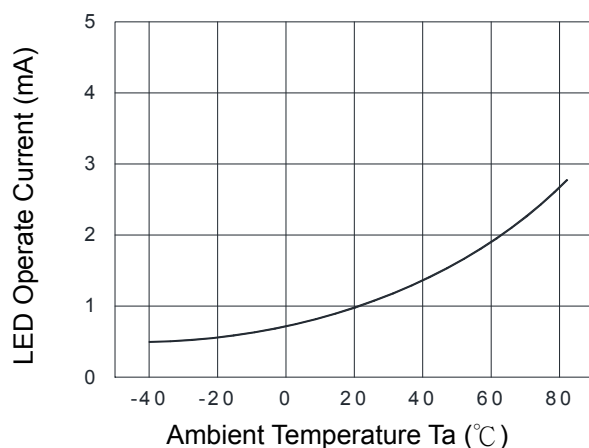
**Fig.3 Turn-on Time vs. Ambient Temperature**



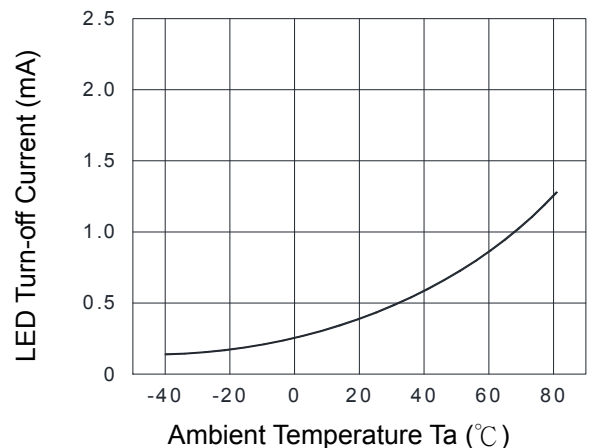
**Fig.4 Turn-off Time vs. Ambient Temperature**



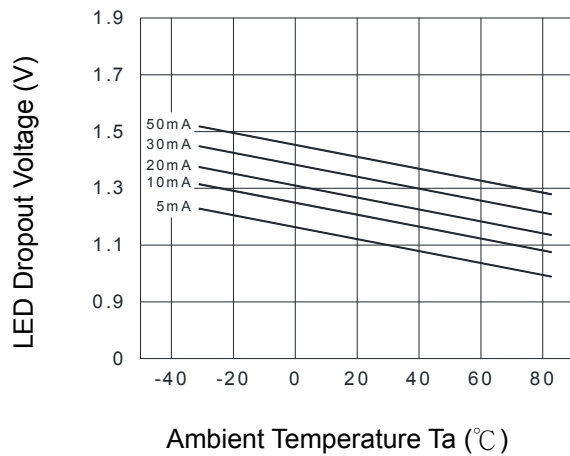
**Fig.5 LED Operate Current vs. Ambient Temperature**



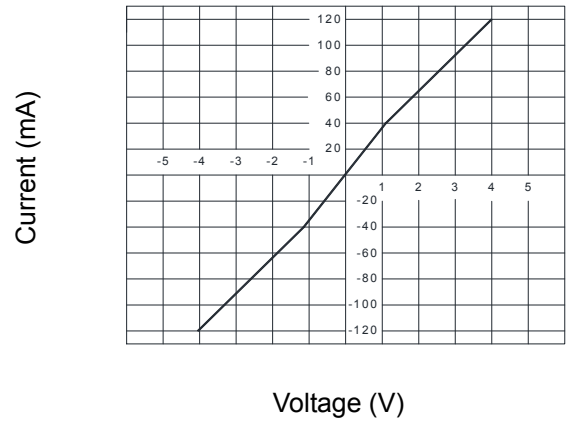
**Fig.6 LED Turn-off Current vs. Ambient Temperature**



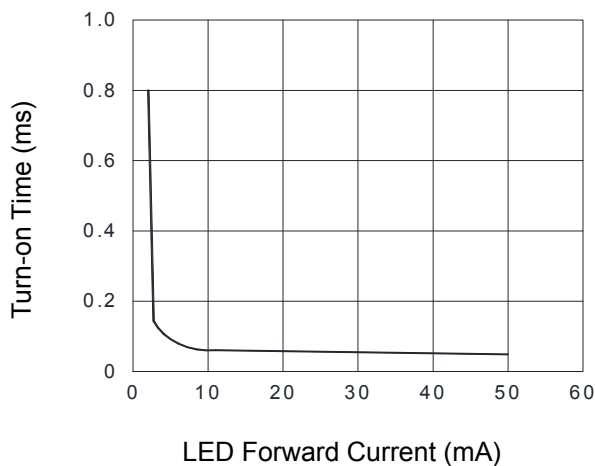
**Fig.7 LED Dropout Voltage vs. Ambient Temperature**



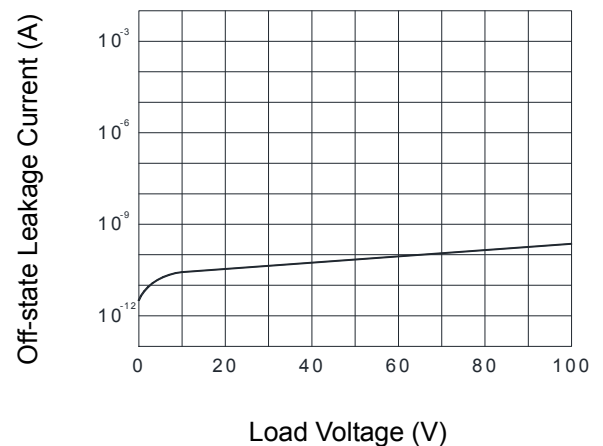
**Fig.8 Voltage vs. Current Characteristics of Output at MOSFET Portion**



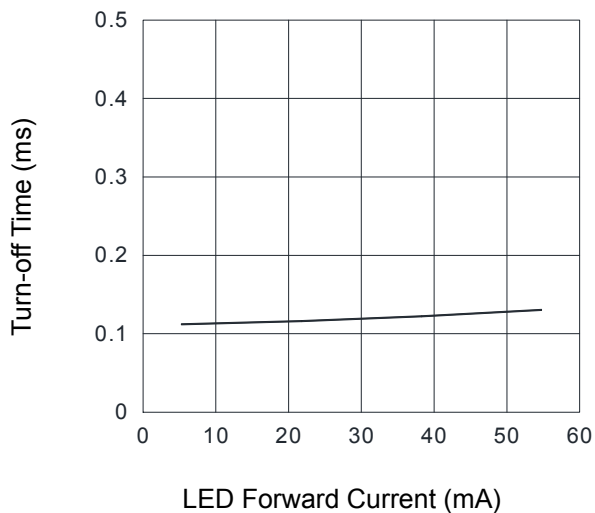
**Fig.9 Turn-on Time vs. LED Forward Current**



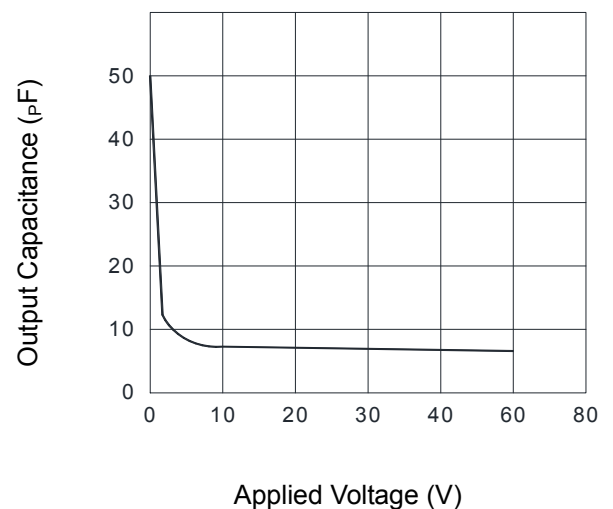
**Fig.10 Off-state Leakage Current vs. Load Voltage**



**Fig.11 Turn-off Time vs. LED Forward Current**

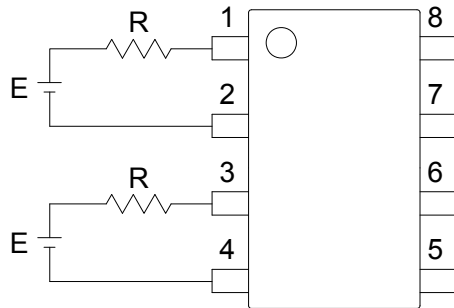


**Fig.12 Output Capacitance vs. Applied Voltage**



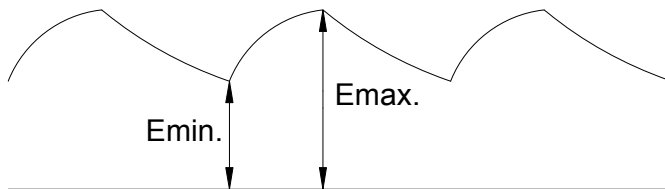
## ● Using Methods

Examples of resistance value to control LED forward current ( $I_F=5\text{mA}$ )

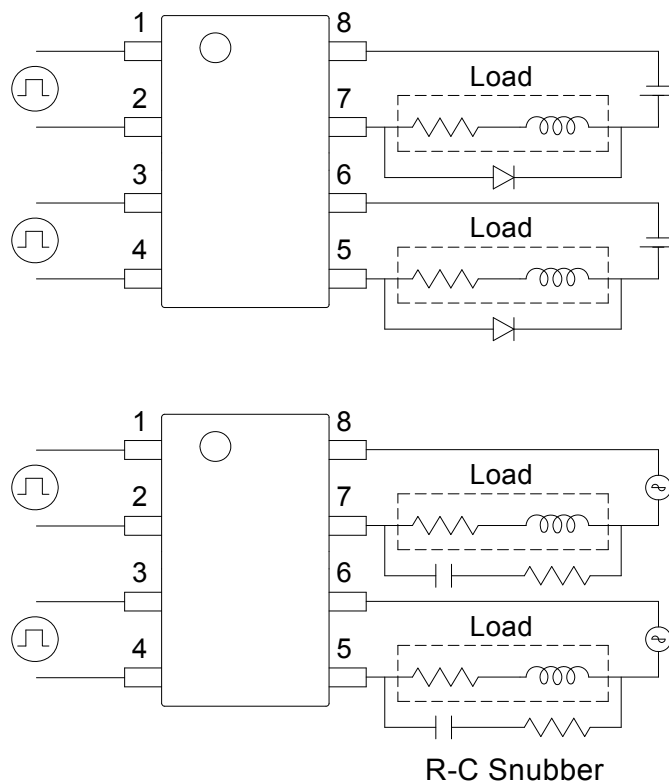


| E    | R                     |
|------|-----------------------|
| 3.3V | Approx. 330 $\Omega$  |
| 5V   | Approx. 640 $\Omega$  |
| 12V  | Approx. 1.9K $\Omega$ |
| 15V  | Approx. 2.5K $\Omega$ |
| 24V  | Approx. 4.1K $\Omega$ |

1. LED forward current must be more than 5mA , at E min.
2. LED forward current must be less than 50mA , at E max.



Regulate the spike voltage generated on the inductive load as follows :

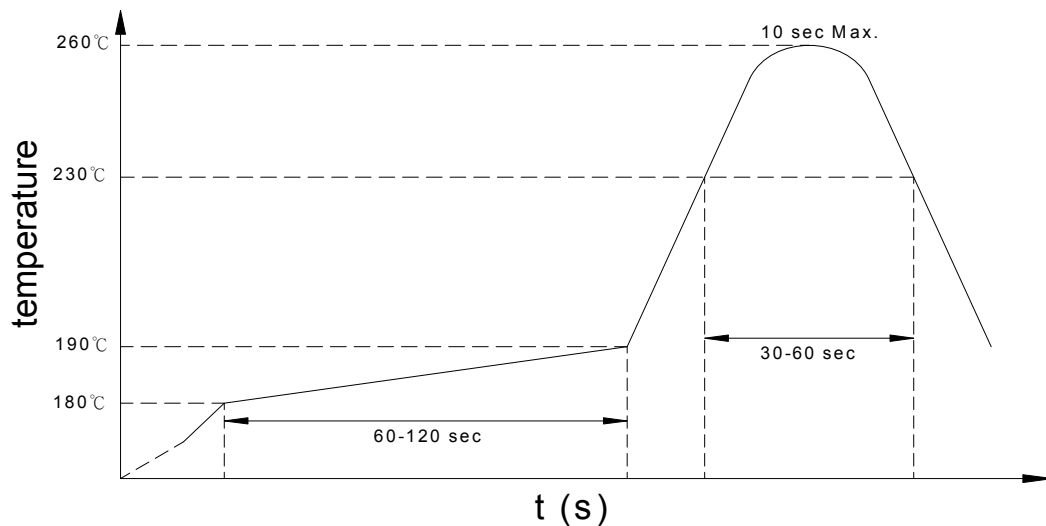


● **Recommended Soldering Conditions**

**(a) Infrared reflow soldering :**

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature: 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec  
Two
- Number of reflows : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
- Flux :

**Recommended Temperature Profile of Infrared Reflow**



**(b) Wave soldering :**

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions: 120°C or below (package surface temperature)
- Number of times : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

**(c) Cautions :**

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.



## ● Numbering System

### NAQW216 X (Y)

#### Note :

NAQW216 = Part No.

X = Lead form option ( blank 、 S or A )

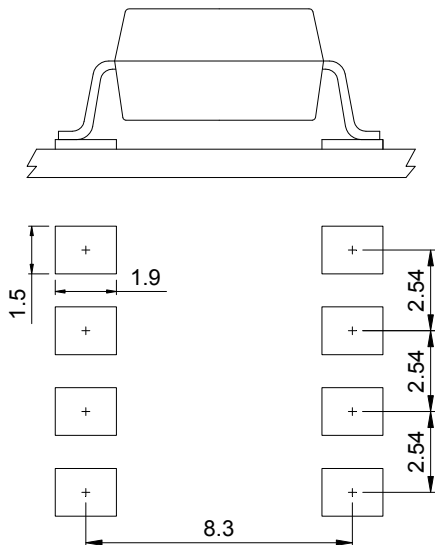
Y = Tape and reel option ( TL 、 TR )

| Option | Description                                                             | Packing quantity    |
|--------|-------------------------------------------------------------------------|---------------------|
| A (TL) | surface mount type package + TL tape & reel option                      | 1000 units per reel |
| A (TR) | surface mount type package + TR tape & reel option                      | 1000 units per reel |
| S (TL) | small outline for surface mount type package +<br>TL tape & reel option | 2000 units per reel |
| S (TR) | small outline for surface mount type package +<br>TR tape & reel option | 2000 units per reel |

## ● Recommended Pad Layout for Surface Mount Lead Form

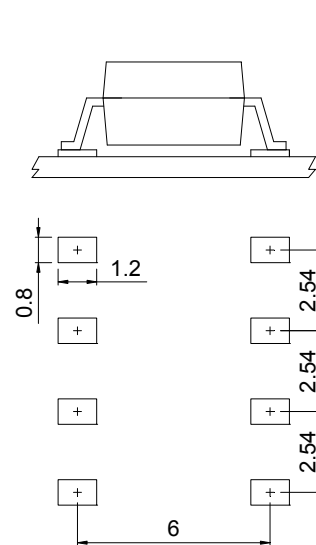
### 1. Surface mount type.

8-pin SMD



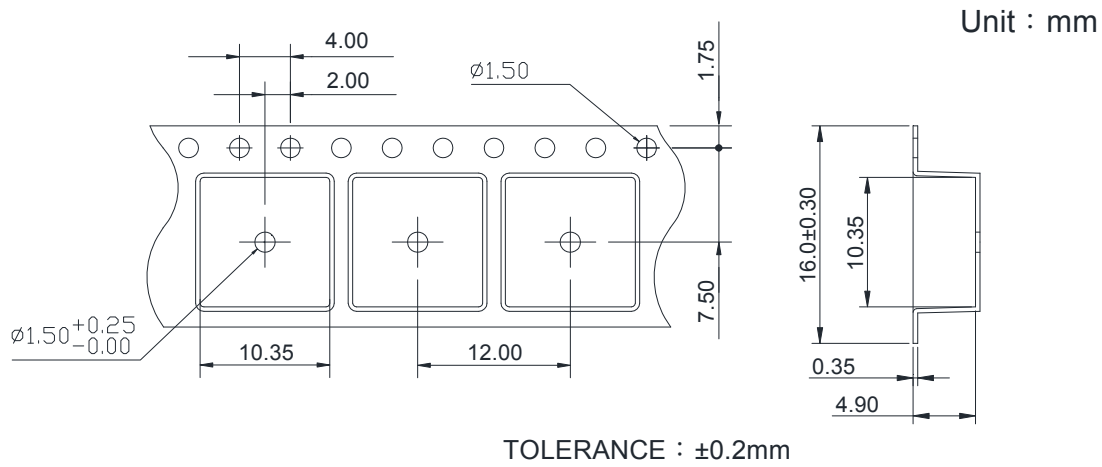
### 2. Small outline for surface mount type.

8-pin SOP



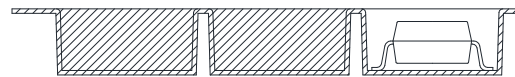
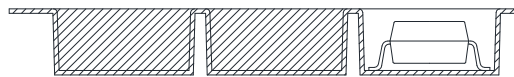
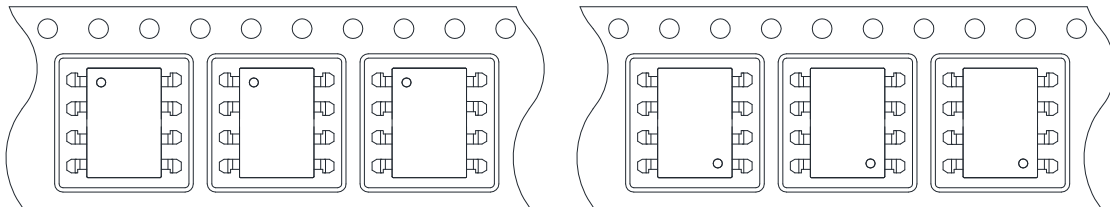
Unit : mm

● 8-pin SMD Carrier Tape & Reel



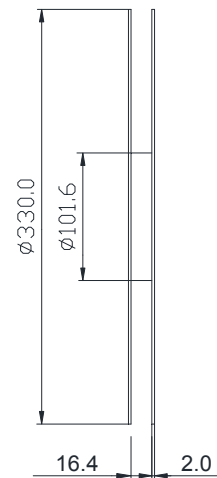
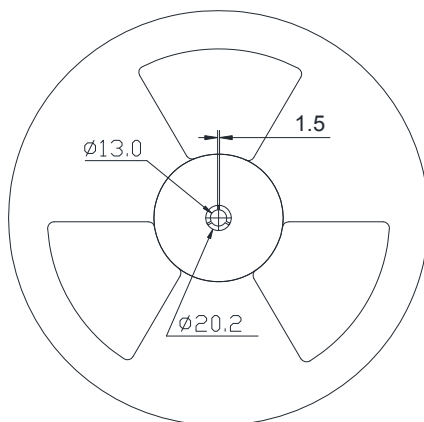
TL

TR

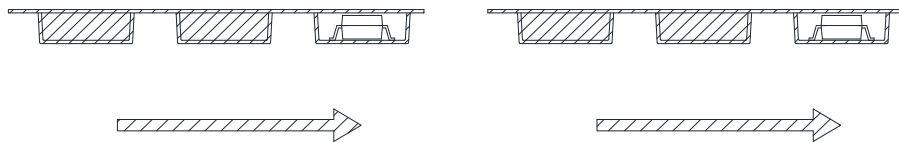
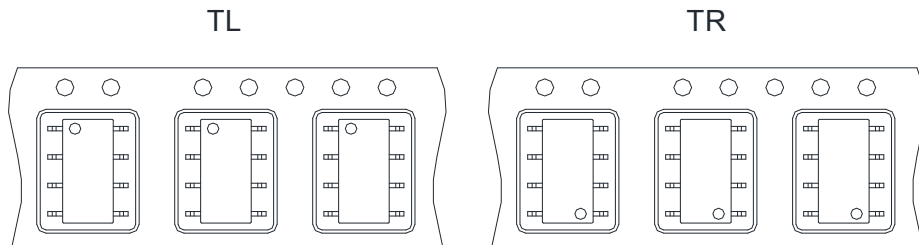
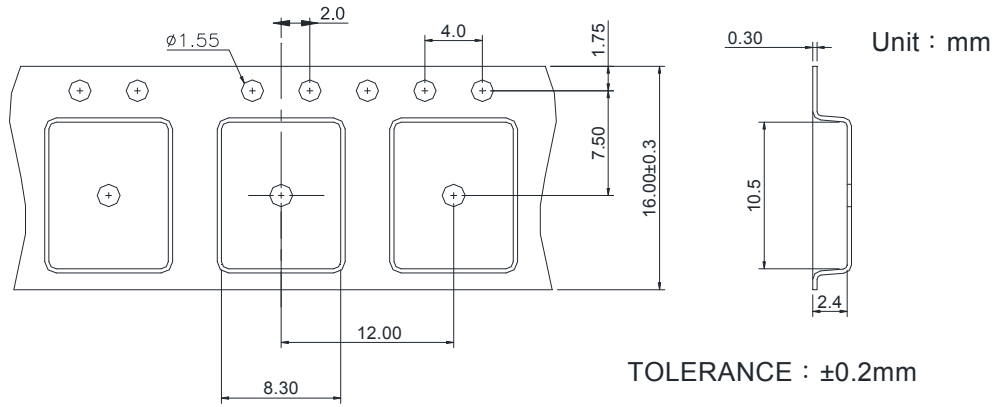


Direction of feed from reel

Direction of feed from reel



● 8-pin SOP Carrier Tape & Reel



Direction of feed from reel

Direction of feed from reel

